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ASIA SHANGHAI



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Shanghai New International Expo
Centre (SNIEC), China

PCIM Asia Shanghai – International Exhibition and
Conference for Power Electronics, Intelligent Motion,
Renewable Energy and Energy Management

Call for Paper 2025

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» Being able to identify the industry's development trends, this makes the conference even more important for industry players to focus on developing the right products and technologies to meet the demands of the future. «

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→ All the selected papers will be published in official conference proceeding, and will have the opportunity to archive in reputable databases: Ei Compendex, IEEE Xplore, IET Inspec-Direct and Scopus.



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→ Establish new contacts and take advantage of networking opportunities with global leading industry brands.



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Submission requirements available at
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Dates to remember

- Submission of abstracts before **4 March 2025**
- Notification of acceptance on **May 2025**
- Submission of full paper before **20 June 2025**
- ★ The presentation language is ENGLISH



Chance to win the awards

The awards will be selected by the Advisory Board from the accepted papers, and will be granted at the conference award ceremony.



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Topics of Interest

1. Advanced Power Semiconductors

- 1.1 High Power Semiconductors
- 1.2 MOSFETs, IGBTs, FREDs & Schottkys
- 1.3 Power Modules and Power Hybrids
- 1.4 SiC Devices
- 1.5 GaN Devices
- 1.6 Other Wide Bandgap Devices
- 1.7 Power Supply Control IC and Power Management ICs
- 1.8 Gate Driver and Device Protection
- 1.9 IPM and Power Electronic Building Blocks

2. Packaging and Reliability

- 2.1 Packaging and Interface Technologies
- 2.2 Advanced Cooling Systems
- 2.3 Thermal Management and Simulations
- 2.4 Power Electronic Components Reliability and Life Time Prediction
- 2.5 Power Embedding
- 2.6 High Power Density Designs
- 2.7 Design Automation and Methodology

3. Passive Components and Integration

- 3.1 Higher Frequency and Low Loss Materials & Techniques for Inductors and Capacitors
- 3.2 Planar Inductors and Transformers and Thin Film Magnetic Component
- 3.3 Filters and Passive Integration

4. AC/DC Converter

- 4.1 High Efficiency/High Density Power Converters/Inverters
- 4.2 Resonant and Quasi Resonant Topologies for Power Supplies
- 4.3 Stand-alone Power Supplies (Adapters) and on Board Supplies
- 4.4 New Topologies (Single Switch, Phase Shift, ZVS, ZCS, ZVZCS)

5. DC/DC Converter

- 5.1 DC/DC Converter Topologies for Enhanced Efficiency and Control
- 5.2 Synchronous Rectification
- 5.3 Smart Battery Management Concepts
- 5.4 Point of Load Converters
- 5.5 New Topologies for Distributed Power Supply Systems (Single or Multi- Stage Architecture, ZVS, ZCS, ZVZCS)

6. Digital Power Conversion

- 6.1 PMBus and other Digital Power Control Protocols
- 6.2 Digital Control for Power Converters
- 6.3 Advantages of Digital Power Conversion and Associated Challenges
- 6.4 System on a Chip (SOC)
- 6.5 Energy Harvesting

7. Motor Drive & Motion Control

- 7.1 Home Appliances
- 7.2 Small Power Motor "General Purpose Drive" with Highly Sophisticated Control Strategies and Low Cost Solutions
- 7.3 New Converter/Inverter Types for Single- and Three Phase Systems
- 7.4 Advanced Motor Concepts for Industrial Application and Traction Drives
- 7.5 New Control Architectures DSP, Microcontroller or FPGA
- 7.6 Advanced Sensor Concepts for Motor Drives
- 7.7 Intelligent Motion Control and Architecture

8. High Frequency Power Electronic Converters and Inverters

- 8.1 Thermal Design, Packaging and EMI Issues
- 8.2 Sensors Specific to Power Electronics
(e.g. Voltage, Current, Power, Frequency, Phase, Temperature)
- 8.3 Techniques to Reduce Switching Losses to Improve Efficiency and Reduce Size and Weight
- 8.4 Wireless Power Transfer

9. Automotive Power Electronics and Electrified Transportation

- 9.1 Hybrid / Electric Vehicle
- 9.2 MOSFET, IGBT and SiC Modules in Motor Traction and Propulsion Applications
- 9.3 DC/DC Conversion in Transportation Systems
- 9.4 Bidirectional DC/DC Converters
- 9.5 Electronics for Powertrain and Power Management
- 9.6 Energy Storage and Management, including Battery Types, Super Capacitors and Fly Wheels
- 9.7 DC Circuit Breaker
- 9.8 Charging Station Technology

10. System Reliability

- 10.1 Reliability and Health Management of Power Electronic Components and Systems
- 10.2 Fail-safe and Fault-tolerant Applications
- 10.3 Redundancy Concepts in Power Electronics
- 10.4 Life Cycle Design and Cost Analysis

11. Power Quality Solutions

- 11.1 UPS Systems and Inverters
- 11.2 Active Power Filter (APF), DVR, SVG
- 11.3 Energy Storage System
(Battery Technologies, Flywheel, Super (ultra) Capacitors)
- 11.4 Harmonics and Power Factor Correction
- 11.5 Electromagnetic Compatibility and Immunity

12. Smart Grid Power Electronics

- 12.1 Grid Inverter Control
- 12.2 Battery Charging and V2G
- 12.3 Energy Storage System and Control
- 12.4 Micro-Grid
- 12.5 Solid State Transformers
- 12.6 Medium Voltage Multilevel Converters
- 12.7 Modular Multilevel Converters
- 12.8 Novel Converter Topologies
- 12.9 Wind Energy Systems
- 12.10 Solar and Photovoltaic Energy Systems
- 12.11 Communication, Cyber Security and Artificial Intelligence

13. Power Electronics in Transmission Systems

- 13.1 FACTS
- 13.2 Converters for Offshore/Onshore HVDC Links
- 13.3 Power Generation, Transmission and Distribution
- 13.4 DC Grids
- 13.5 HVDC Systems
- 13.6 Digital Twin for Transmission Equipment

Prominent Conference Speakers in 2024

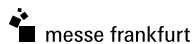


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